News Release

November 5, 2026
JX Advanced Metals Corporation

Expand Production Capacity for Upinorg High-Purity Copper Sulfate
- New Production Line at Ibaraki Office (Hitachi Area)
to Meet Growing Demand in the Advanced Semiconductor Market -

JX Advanced Metals Corporation (President: Hayashi Yoichi; "the Company") has decided to install an additional production line at its Ibaraki Office (Hitachi area) to meet growing demand for its Upinorg high-purity copper sulfate. The investment will increase production capacity by approximately 50% compared with the first half of fiscal 2026. The new facilities will begin operations in phases from the second half of fiscal 2027.

Upinorg is a high-purity copper sulfate manufactured using the Company's proprietary purification technology. It achieves extremely low levels of impurities compared with typical copper sulfate derived from ores or waste solutions, allowing the stable production of high-purity products. Upinorg has been widely adopted by customers for use in copper plating solutions for through-holes[1] and via filling[2] in printed circuit boards, and also as a material for damascene processes[3] in semiconductor manufacturing.

As one of the Company's core products in its plating-related business, Upinorg has been supplied for more than 40 years and is highly regarded in the market due to the Company's advanced purification technology and stable supply capabilities. Recently, demand has been increasing, driven primarily by the expansion of the advanced semiconductor market for generative AI applications. In particular, demand is rising rapidly for high-quality copper plating materials used in advanced packaging, which supports higher semiconductor performance and greater integration, as well as in applications such as HBM (High Bandwidth Memory). The Company expects this growth trend to continue. At the same time, customers are increasingly seeking the long-term, stable supply of high-quality products.

In light of these market conditions, the Company has decided to make this investment and install a new production line for Upinorg. Through this investment, the Company will expand production capacity and further strengthen its framework for ensuring stable supply, while also pursuing additional improvements in product quality and supply reliability. As a global player in advanced materials, the Company will continue to contribute to the advancement of society and technological innovation.

Reference

Note 1: Through-hole
A hole that passes through a printed circuit board. Copper plating is applied to the inner wall of the hole to electrically connect the wiring layers on the front and back surfaces and within the board.

Note 2: Via filling
A technology in which vias (microscopic holes) that electrically connect different layers of a printed circuit board are filled with copper plating.

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Note 3: Damascene process

A semiconductor manufacturing process in which microscopic trenches and holes are formed in an insulating layer and filled with copper, after which excess copper on the surface is polished away to form copper interconnects.



Upinorg high-purity copper sulfate

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